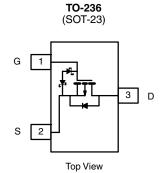




P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A) ^a	Q _g (Typ.)			
- 20	0.0320 at V _{GS} = - 4.5 V	- 5.9				
	0.0410 at V _{GS} = - 2.5 V	- 5.2	13.8 nC			
	0.0675 at V _{GS} = - 1.8 V	- 4.3				



Si2365EDS (H5)* * Marking Code

Ordering Information:

Si2365EDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

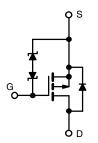
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Built-in ESD Protection
 - Typical ESD Performance 3000 V
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



HALOGEN FREE

APPLICATIONS

- Power Management for Portable and Consumer
 - Load Switches
 - DC/DC Converters



P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	- 20	V		
Gate-Source Voltage	V_{GS}	± 8			
	T _C = 25 °C		- 5.9		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C	,	- 4.7		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 4.5 ^{b, c}		
	T _A = 70 °C		- 3.6 ^{b, c}	А	
Pulsed Drain Current (t = 300 μs)	I _{DM}	- 20			
Continuous Source-Drain Diode Current	T _C = 25 °C	_	- 1.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 1 ^{b, c}		
	T _C = 25 °C		1.7		
Maximum Dawar Dissipation	T _C = 70 °C	В	1.1	١٨/	
Maximum Power Dissipation	T _A = 25 °C	P _D	1 ^{b, c}	– w	
	T _A = 70 °C		0.6 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature		260			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	100	130	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	- °C/vv	

Notes:

- a. $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 175 °C/W.

Si2365EDS

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static		V 0.V I 050 vA			1	.,		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V		
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 14		mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			2.5				
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 0.4		- 1	V		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 10			
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	μΑ		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1			
	500	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 15			Α		
		$V_{GS} = -4.5 \text{ V}, I_D = -4 \text{ A}$		0.0265	0.0320			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -4 \text{ A}$		0.0340	0.0410	Ω		
		$V_{GS} = -1.8 \text{ V}, I_D = -2 \text{ A}$		0.0465	0.0675			
Dynamic ^b								
Total Gate Charge	0	V _{DS} = - 10 V, V _{GS} = - 8 V, I _D = - 4.5 A		23.8	36	nC		
Total Gate Charge	Q_g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 4.5 A		13.8	21			
Gate-Source Charge	Q_{gs}			1.9				
Gate-Drain Charge	Q_{gd}			3				
Gate Resistance	R_{g}	f = 1 MHz	2.2	11	22	Ω		
Turn-On Delay Time	t _{d(on)}			22	33			
Rise Time	t _r	V_{DD} = - 10 V, R_L = 2.8 Ω		21	32			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 3.6 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		62	93			
Fall Time	t _f			14	21			
Turn-On Delay Time	t _{d(on)}			9	18	ns		
Rise Time	t _r	$V_{DD} = -10 \text{ V, R}_{L} = 2.8 \Omega$		6	12			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 3.6 A, V_{GEN} = - 8 V, R_g = 1 Ω		65	98			
Fall Time	t _f			15	23	1		
Drain-Source Body Diode Characterist	ics	<u> </u>						
Continuous Source-Drain Diode Current	ious Source-Drain Diode Current I_S $T_C = 25 ^{\circ}C$				- 1.4	۸		
Pulse Diode Forward Current	I _{SM}				- 20	Α		
Body Diode Voltage	V_{SD}	I _S = - 3.6 A, V _{GS} = 0 V		- 0.8	- 1.2	V		
Body Diode Reverse Recovery Time t _{rr}				13	20	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	1 2 6 A dl/dt 100 A/vo T 25 90		5	10	nC		
Reverse Recovery Fall Time	t _a	$I_F = -3.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		8		ns		
Reverse Recovery Rise Time	t _b			5				

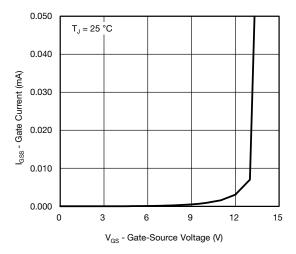
Notes:

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

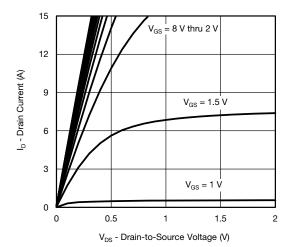
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



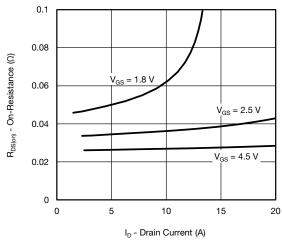
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



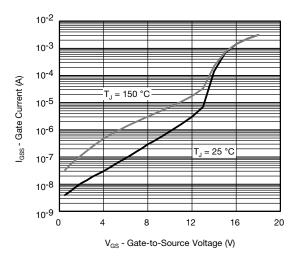
Gate Current vs. Gate-Source Voltage



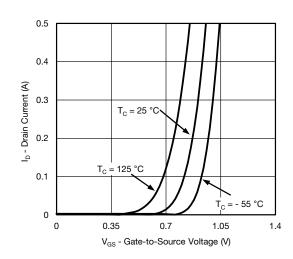
Output Characteristics



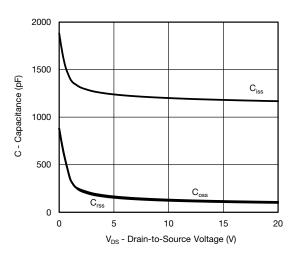
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



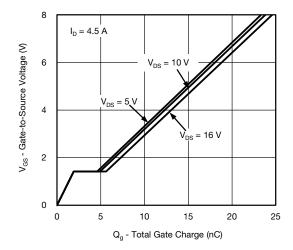
Transfer Characteristics



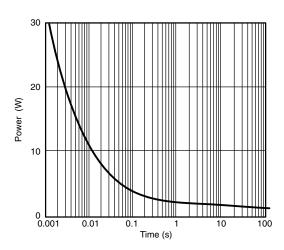
Capacitance

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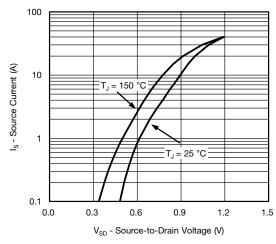
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



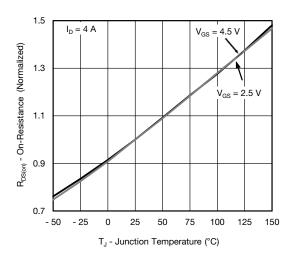
Gate Charge



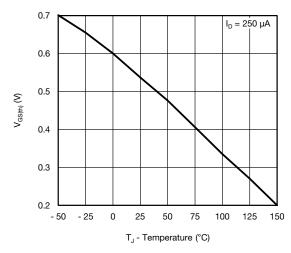
Single Pulse Power, Junction-to-Ambient



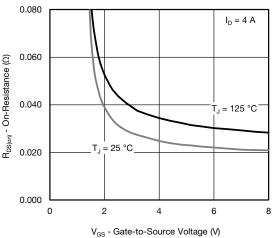
Soure-Drain Diode Forward Voltage



On-Resistance vs. Junction Temperature



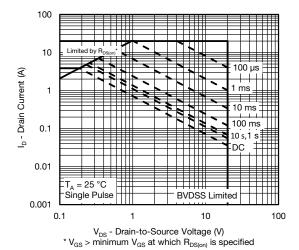
Threshold Voltage



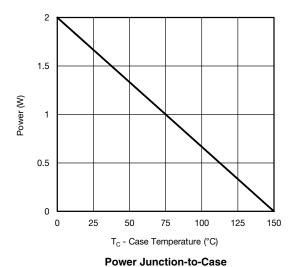
On-Resistance vs. Gate-to-Source Voltage

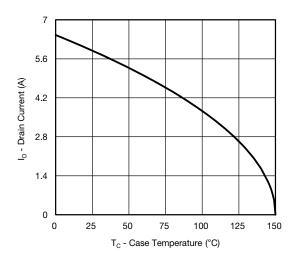


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

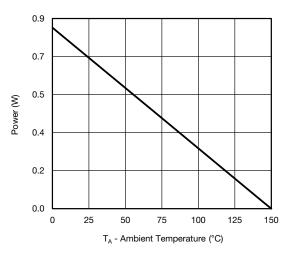


Safe Operating Area, Junction-to-Ambient





Current Derating*

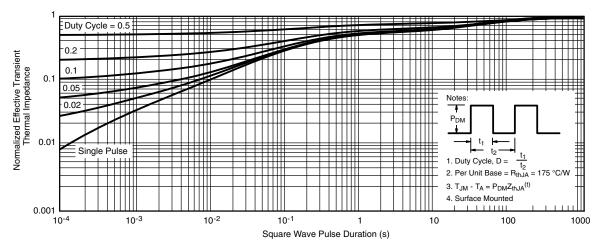


Power Junction-to-Ambient

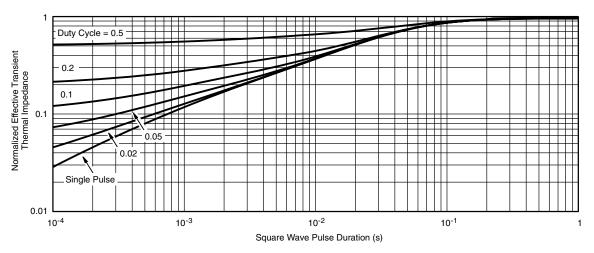
 $^{^{\}star}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.9	5 BSC	0.037	4 Ref	
e ₁	1.9	1.90 BSC		8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.5	50 Ref	0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



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